

ABSTRACT

A packaging structure for a semiconductor device includes a substrate surface-mountable on a mounting surface of a circuit board. The substrate has a first side facing away from the mounting surface and a second side being on the same side of the structure as the mounting surface. A recess is formed in the second side of the substrate. A semiconductor die having a first side and a second side is mounted in the recess, with the first side of the semiconductor die facing away from the mounting surface and a portion of the first side of the semiconductor die bonded to the substrate within the recess.